



# PMV74EPE

30 V, P-channel Trench MOSFET

20 August 2019

Product data sheet

## 1. General description

P-channel enhancement mode Field-Effect Transistor (FET) in a small SOT23 (TO-236AB) Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

## 2. Features and benefits

- Logic-level compatible
- Very fast switching
- Trench MOSFET technology
- ElectroStatic Discharge (ESD) protection > 2 kV HBM

## 3. Applications

- Relay driver
- High-speed line driver
- High-side load switch
- Switching circuits

## 4. Quick reference data

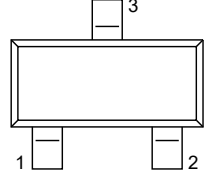
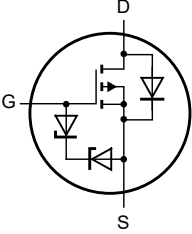
Table 1. Quick reference data

| Symbol                        | Parameter                        | Conditions   | Min | Typ | Max  | Unit |
|-------------------------------|----------------------------------|--|-----|-----|------|------|
| $V_{DS}$                      | drain-source voltage             | $T_j = 25\text{ °C}$   | -   | -   | -30  | V    |
| $V_{GS}$                      | gate-source voltage              |  | -20 | -   | 20   | V    |
| $I_D$                         | drain current                    | $V_{GS} = -10\text{ V}; T_{amb} = 25\text{ °C}; t \leq 5\text{ s}$ | [1] | -   | -3.4 | A    |
| <b>Static characteristics</b> |                                  |  |     |     |      |      |
| $R_{DSon}$                    | drain-source on-state resistance | $V_{GS} = -10\text{ V}; I_D = -2.8\text{ A}; T_j = 25\text{ °C}$   | -   | 74  | 90   | mΩ   |

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and mounting pad for drain 6 cm<sup>2</sup>.

## 5. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description | Simplified outline  | Graphic symbol   |
|-----|--------|-------------|---|--|
| 1   | G      | gate        |  <p>TO-236AB (SOT23)</p> |  <p>017aaa259</p> |
| 2   | S      | source      |   |  |
| 3   | D      | drain       |   |  |

## 6. Ordering information

Table 3. Ordering information

| Type number | Package  |  |         |
|-------------|----------|--|---------|
|             | Name     | Description                              | Version |
| PMV74EPE    | TO-236AB | plastic surface-mounted package; 3 leads | SOT23   |

## 7. Marking

Table 4. Marking codes

| Type number | Marking code <sup>[1]</sup> |
|-------------|-----------------------------|
| PMV74EPE    | 2P%                         |

[1] % = placeholder for manufacturing site code

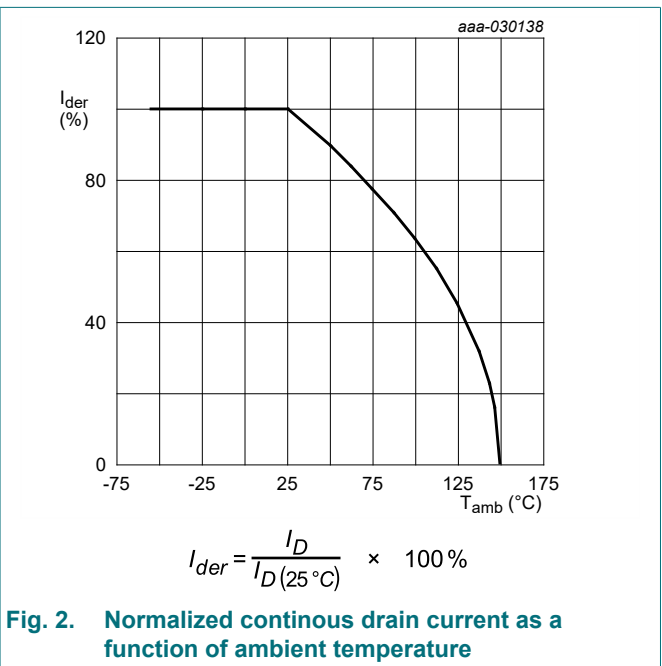
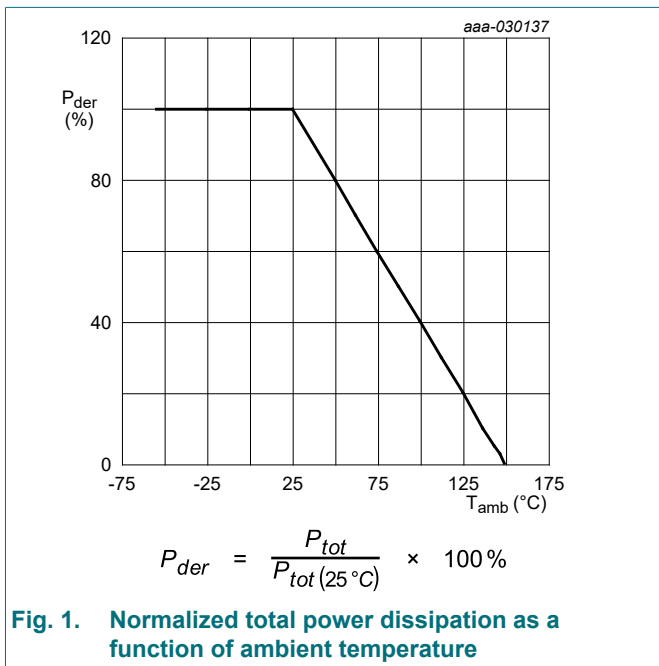
## 8. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol                    | Parameter               | Conditions   | Min | Max | Unit |    |
|---------------------------|-------------------------|--|-----|-----|------|----|
| V <sub>DS</sub>           | drain-source voltage    | T <sub>j</sub> = 25 °C   | -   | -30 | V    |    |
| V <sub>GS</sub>           | gate-source voltage     |  | -20 | 20  | V    |    |
| I <sub>D</sub>            | drain current           | V <sub>GS</sub> = -10 V; T <sub>amb</sub> = 25 °C; t ≤ 5 s     | [1] | -   | -3.4 | A  |
|                           |                         | V <sub>GS</sub> = -10 V; T <sub>amb</sub> = 25 °C              | [1] | -   | -2.8 | A  |
|                           |                         | V <sub>GS</sub> = -10 V; T <sub>amb</sub> = 100 °C             | [1] | -   | -1.8 | A  |
| I <sub>DM</sub>           | peak drain current      | T <sub>amb</sub> = 25 °C; single pulse; t <sub>p</sub> ≤ 10 μs | -   | -11 | A    |    |
| P <sub>tot</sub>          | total power dissipation | T <sub>amb</sub> = 25 °C                                       | [2] | -   | 510  | mW |
|                           |                         |  | [1] | -   | 1    | W  |
|                           |                         | T <sub>sp</sub> = 25 °C  |     | -   | 6.4  | W  |
| T <sub>j</sub>            | junction temperature    |  | -55 | 150 | °C   |    |
| T <sub>amb</sub>          | ambient temperature     |  | -55 | 150 | °C   |    |
| T <sub>stg</sub>          | storage temperature     |  | -65 | 150 | °C   |    |
| <b>Source-drain diode</b> |                         |  |     |     |      |    |
| I <sub>S</sub>            | source current          | T <sub>amb</sub> = 25 °C                                       | [1] | -   | -1.1 | A  |

- [1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and mounting pad for drain 6 cm<sup>2</sup>.
- [2] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.



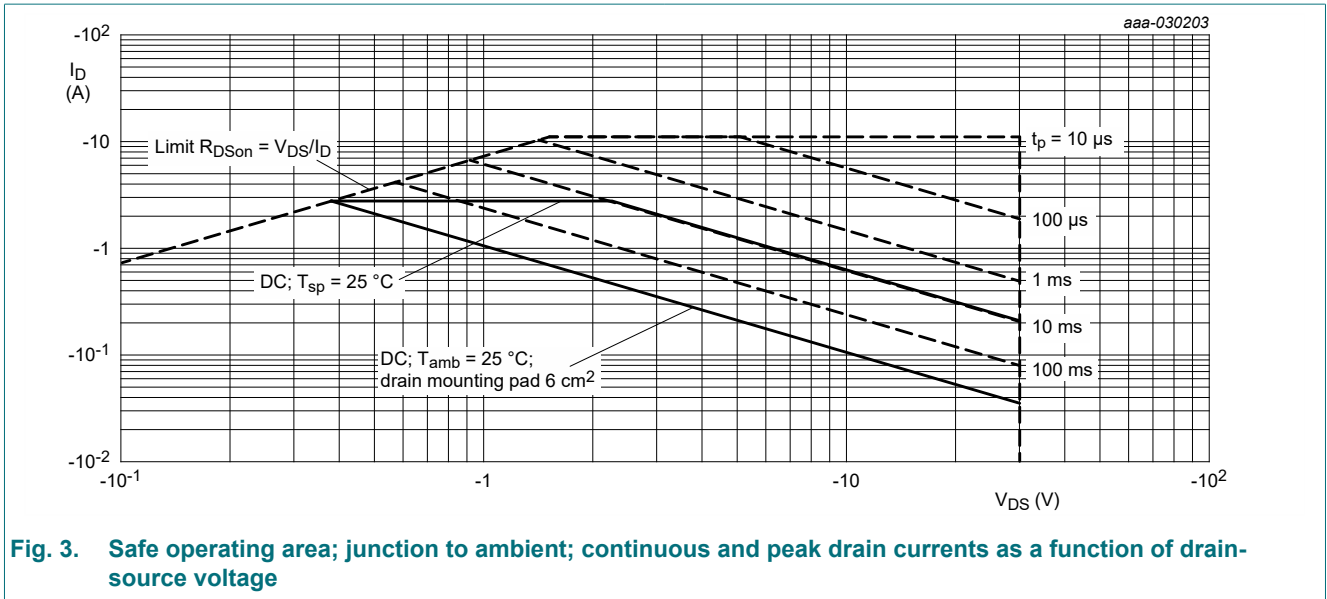


Fig. 3. Safe operating area; junction to ambient; continuous and peak drain currents as a function of drain-source voltage

## 9. Thermal characteristics

Table 6. Thermal characteristics

| Symbol         | Parameter  | Conditions                |     | Min | Typ | Max | Unit |
|----------------|--|---------------------------|-----|-----|-----|-----|------|
| $R_{th(j-a)}$  | thermal resistance from junction to ambient      | in free air               | [1] | -   | 212 | 244 | K/W  |
|                |  |                           | [2] | -   | 104 | 119 | K/W  |
|                |  | in free air; $t \leq 5$ s | [2] | -   | 69  | 79  | K/W  |
| $R_{th(j-sp)}$ | thermal resistance from junction to solder point |                           |     | -   | 17  | 20  | K/W  |

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and mounting pad for drain 6 cm<sup>2</sup>.

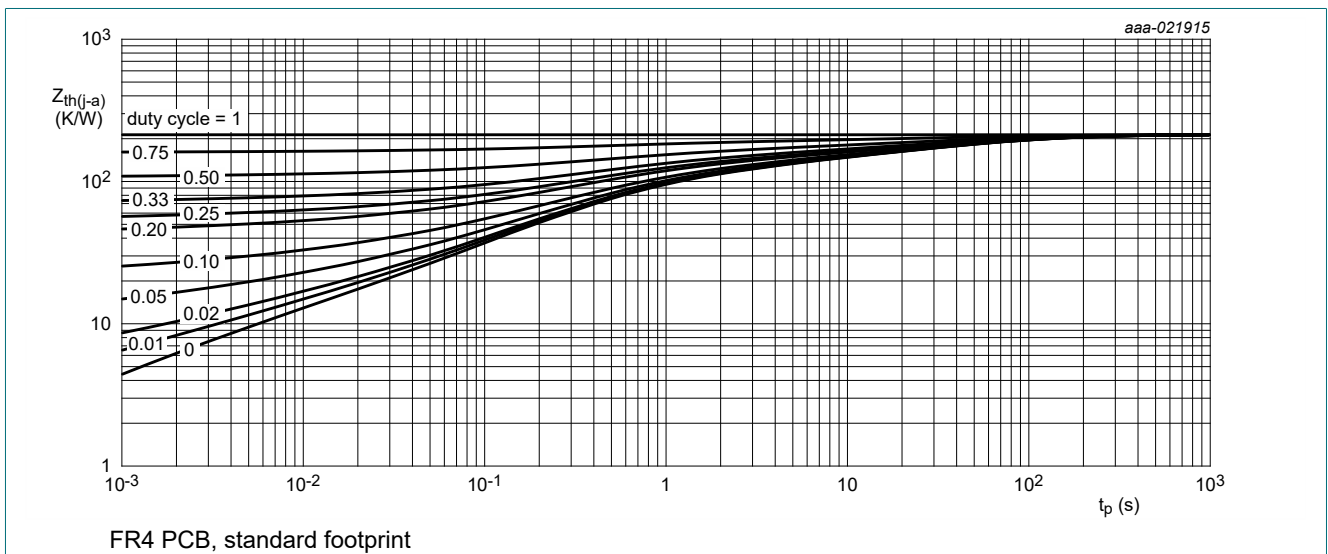


Fig. 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

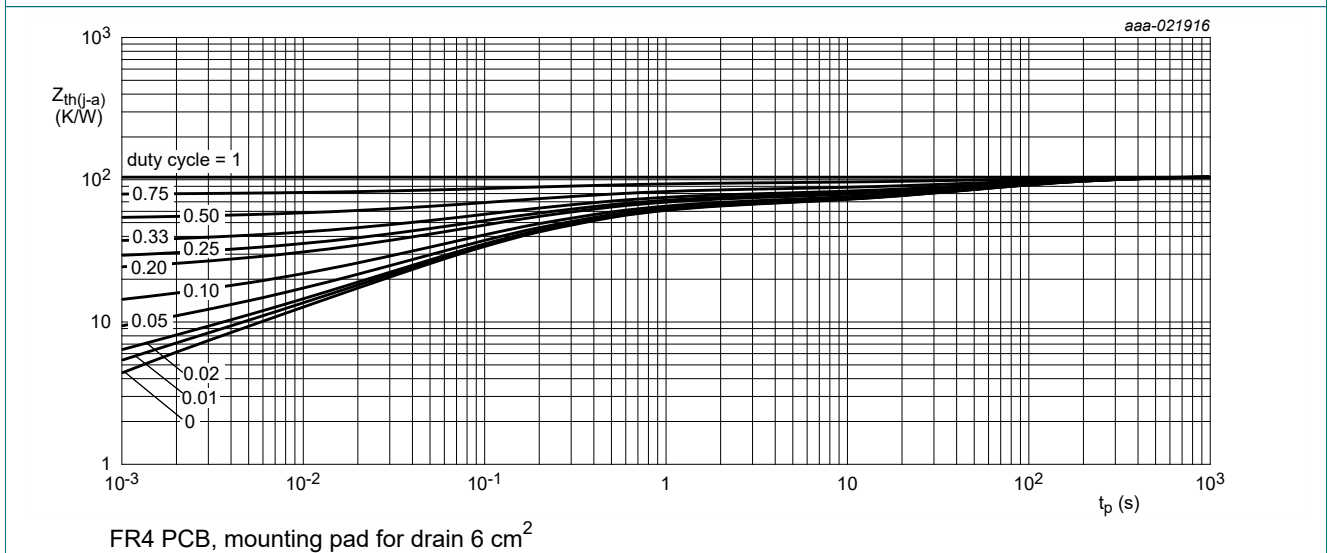


Fig. 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

## 10. Characteristics

Table 7. Characteristics

| Symbol                         | Parameter                        | Conditions  | Min | Typ  | Max  | Unit       |
|--------------------------------|----------------------------------|---|-----|------|------|------------|
| <b>Static characteristics</b>  |                                  |   |     |      |      |            |
| $V_{(BR)DSS}$                  | drain-source breakdown voltage   | $I_D = -250 \mu A$ ; $V_{GS} = 0 V$ ; $T_j = 25 \text{ }^\circ C$   | -30 | -    | -    | V          |
| $V_{GSth}$                     | gate-source threshold voltage    | $I_D = -250 \mu A$ ; $V_{DS} = V_{GS}$ ; $T_j = 25 \text{ }^\circ C$  | -1  | -2   | -3   | V          |
| $I_{DSS}$                      | drain leakage current            | $V_{DS} = -30 V$ ; $V_{GS} = 0 V$ ; $T_j = 25 \text{ }^\circ C$   | -   | -    | -1   | $\mu A$    |
| $I_{GSS}$                      | gate leakage current             | $V_{GS} = 20 V$ ; $V_{DS} = 0 V$ ; $T_j = 25 \text{ }^\circ C$  | -   | -    | 10   | $\mu A$    |
|                                |                                  | $V_{GS} = -20 V$ ; $V_{DS} = 0 V$ ; $T_j = 25 \text{ }^\circ C$   | -   | -    | -10  | $\mu A$    |
|                                |                                  | $V_{GS} = 10 V$ ; $V_{DS} = 0 V$ ; $T_j = 25 \text{ }^\circ C$  | -   | -    | 2    | $\mu A$    |
|                                |                                  | $V_{GS} = -10 V$ ; $V_{DS} = 0 V$ ; $T_j = 25 \text{ }^\circ C$   | -   | -    | -2   | $\mu A$    |
| $R_{DSon}$                     | drain-source on-state resistance | $V_{GS} = -10 V$ ; $I_D = -2.8 A$ ; $T_j = 25 \text{ }^\circ C$   | -   | 74   | 90   | m $\Omega$ |
|                                |                                  | $V_{GS} = -10 V$ ; $I_D = -2.8 A$ ; $T_j = 150 \text{ }^\circ C$  | -   | 112  | 137  | m $\Omega$ |
|                                |                                  | $V_{GS} = -4.5 V$ ; $I_D = -2.1 A$ ; $T_j = 25 \text{ }^\circ C$  | -   | 116  | 150  | m $\Omega$ |
| $g_{fs}$                       | forward transconductance         | $V_{DS} = -10 V$ ; $I_D = -2.7 A$ ; $T_j = 25 \text{ }^\circ C$   | -   | 12   | -    | S          |
| $R_G$                          | gate resistance                  | $f = 1 \text{ MHz}$   | -   | 12   | -    | $\Omega$   |
| <b>Dynamic characteristics</b> |                                  |   |     |      |      |            |
| $Q_{G(tot)}$                   | total gate charge                | $V_{DS} = -15 V$ ; $I_D = -2.7 A$ ; $V_{GS} = -10 V$ ;<br>$T_j = 25 \text{ }^\circ C$                           | -   | 5.7  | 10   | nC         |
| $Q_{GS}$                       | gate-source charge               |   | -   | 1.2  | -    | nC         |
| $Q_{GD}$                       | gate-drain charge                |   | -   | 1.1  | -    | nC         |
| $C_{iss}$                      | input capacitance                | $V_{DS} = -15 V$ ; $f = 1 \text{ MHz}$ ; $V_{GS} = 0 V$ ;<br>$T_j = 25 \text{ }^\circ C$                        | -   | 356  | -    | pF         |
| $C_{oss}$                      | output capacitance               |   | -   | 60   | -    | pF         |
| $C_{rss}$                      | reverse transfer capacitance     |   | -   | 38   | -    | pF         |
| $t_{d(on)}$                    | turn-on delay time               | $V_{DS} = -15 V$ ; $I_D = -2.7 A$ ; $V_{GS} = -10 V$ ;<br>$R_{G(ext)} = 6 \Omega$ ; $T_j = 25 \text{ }^\circ C$ | -   | 5    | -    | ns         |
| $t_r$                          | rise time                        |   | -   | 11   | -    | ns         |
| $t_{d(off)}$                   | turn-off delay time              |   | -   | 19   | -    | ns         |
| $t_f$                          | fall time                        |   | -   | 8    | -    | ns         |
| <b>Source-drain diode</b>      |                                  |   |     |      |      |            |
| $V_{SD}$                       | source-drain voltage             | $I_S = -1.1 A$ ; $V_{GS} = 0 V$ ; $T_j = 25 \text{ }^\circ C$   | -   | -0.8 | -1.2 | V          |

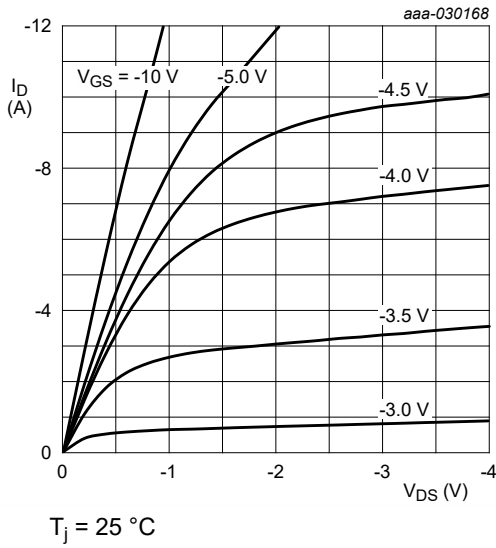


Fig. 6. Output characteristics: drain current as a function of drain-source voltage; typical values

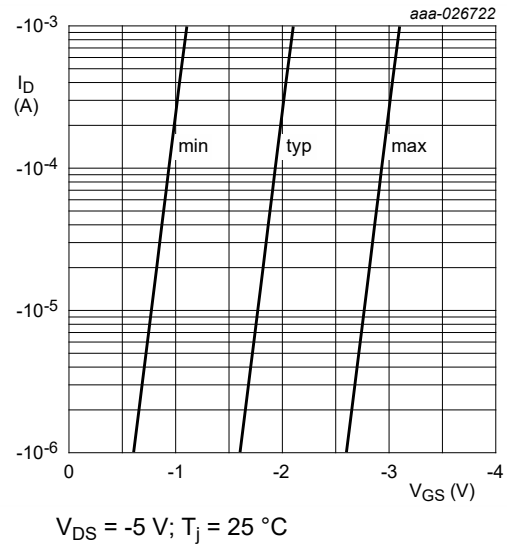


Fig. 7. Sub-threshold drain current as a function of gate-source voltage

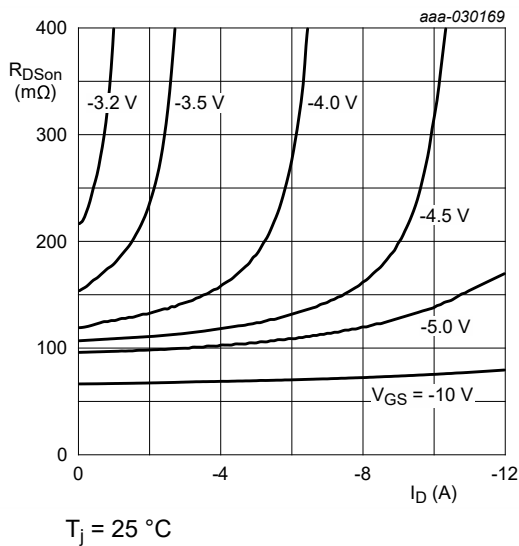


Fig. 8. Drain-source on-state resistance as a function of drain current; typical values

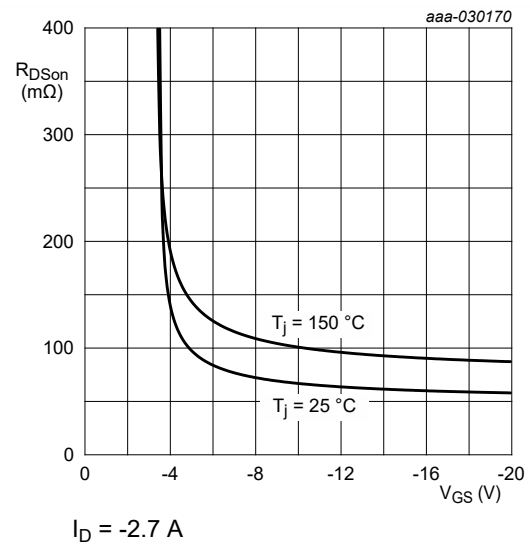
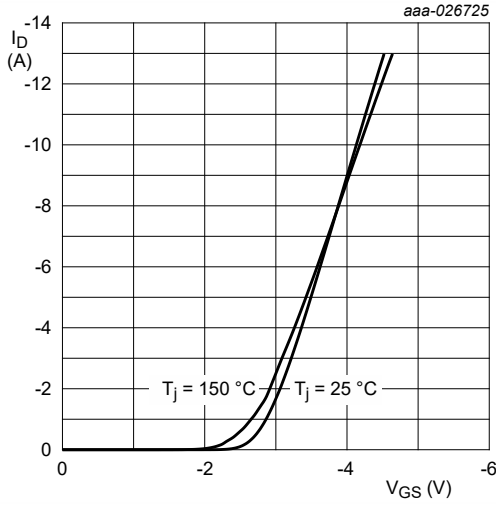
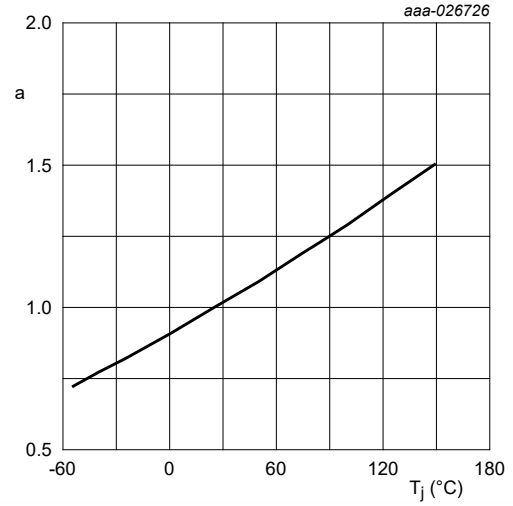


Fig. 9. Drain-source on-state resistance as a function of gate-source voltage; typical values



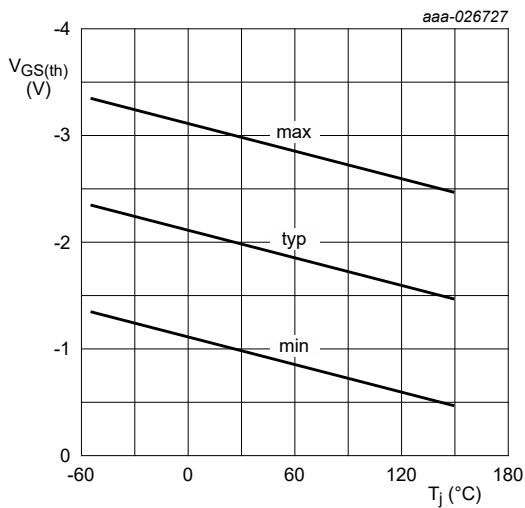
$$V_{DS} > I_D \times R_{DSon}$$

Fig. 10. Transfer characteristics: drain current as a function of gate-source voltage; typical values



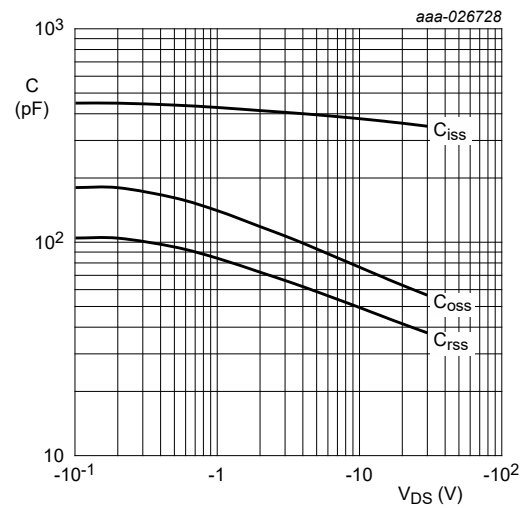
$$a = \frac{R_{DSon}}{R_{DSon(25^\circ C)}}$$

Fig. 11. Normalized drain-source on-state resistance as a function of junction temperature; typical values



$$I_D = -250 \mu A; V_{DS} = V_{GS}$$

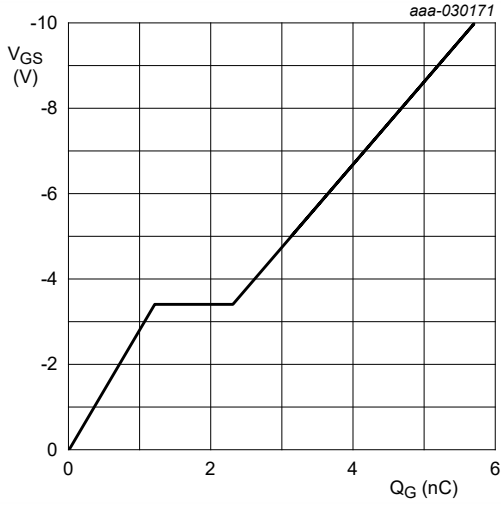
Fig. 12. Gate-source threshold voltage as a function of junction temperature



$$f = 1 \text{ MHz}; V_{GS} = 0 \text{ V}$$

Fig. 13. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values





$I_D = -2.7 \text{ A}; V_{DS} = -15 \text{ V}; T_{amb} = 25 \text{ }^\circ\text{C}$

Fig. 14. Gate-source voltage as a function of gate charge; typical values

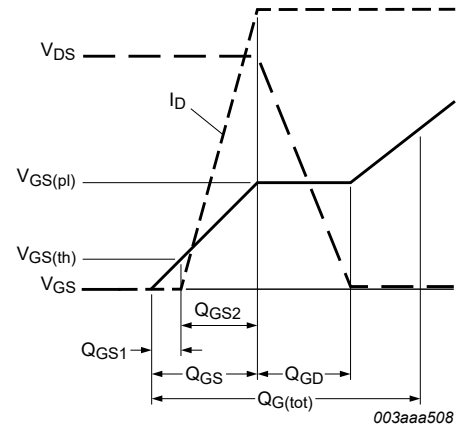
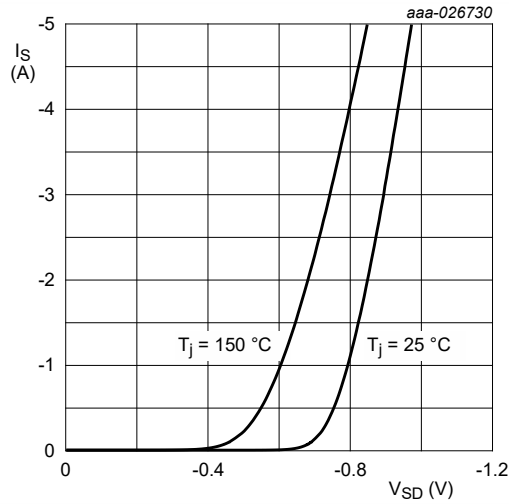


Fig. 15. Gate charge waveform definitions



$V_{GS} = 0 \text{ V}$

Fig. 16. Source current as a function of source-drain voltage; typical values

## 11. Test information

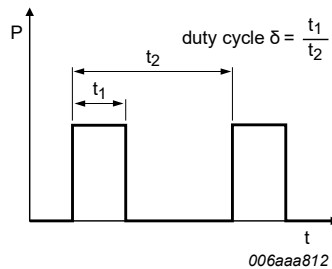


Fig. 17. Duty cycle definition

## 12. Package outline

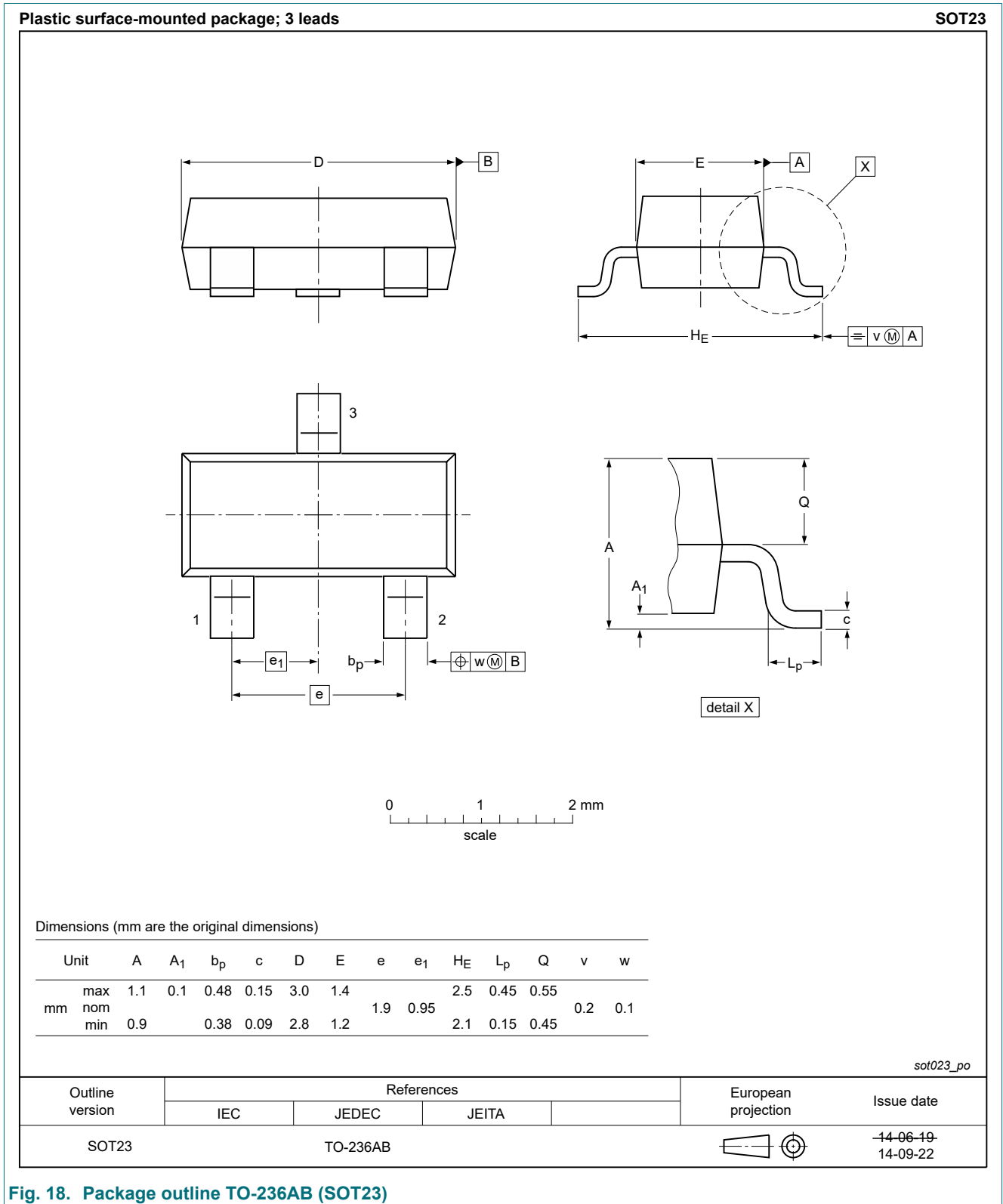


Fig. 18. Package outline TO-236AB (SOT23)

### 13. Soldering

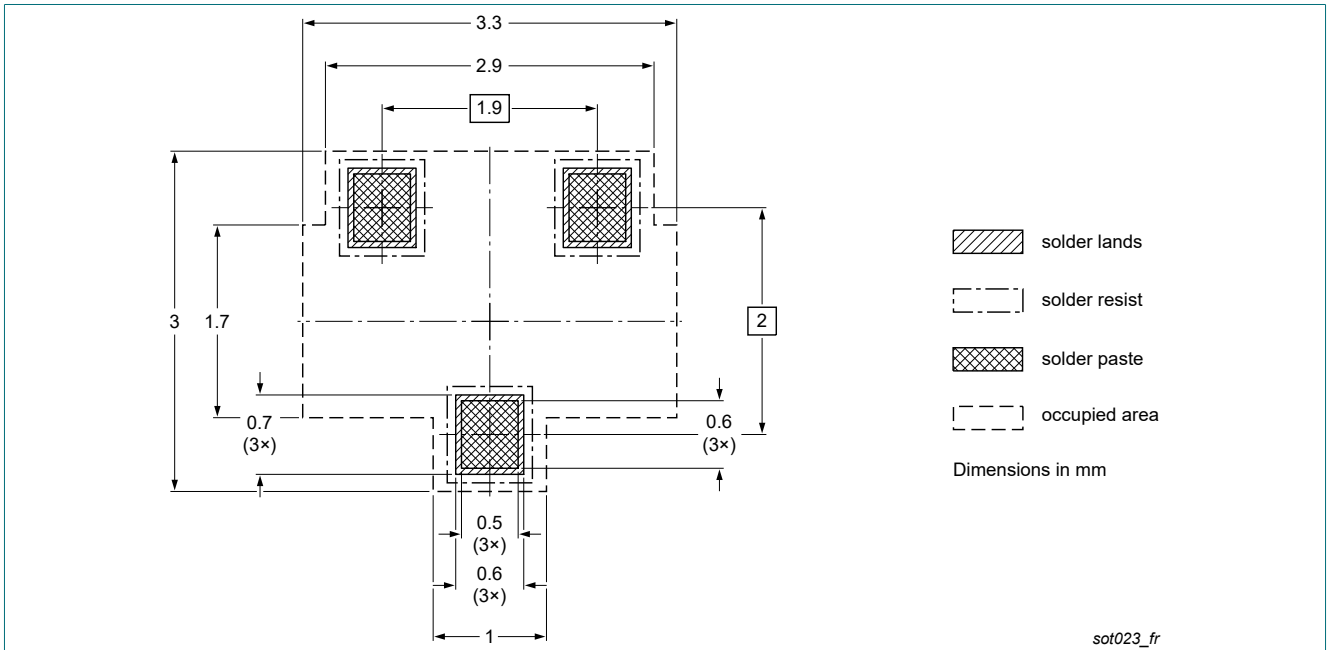


Fig. 19. Reflow soldering footprint for TO-236AB (SOT23)

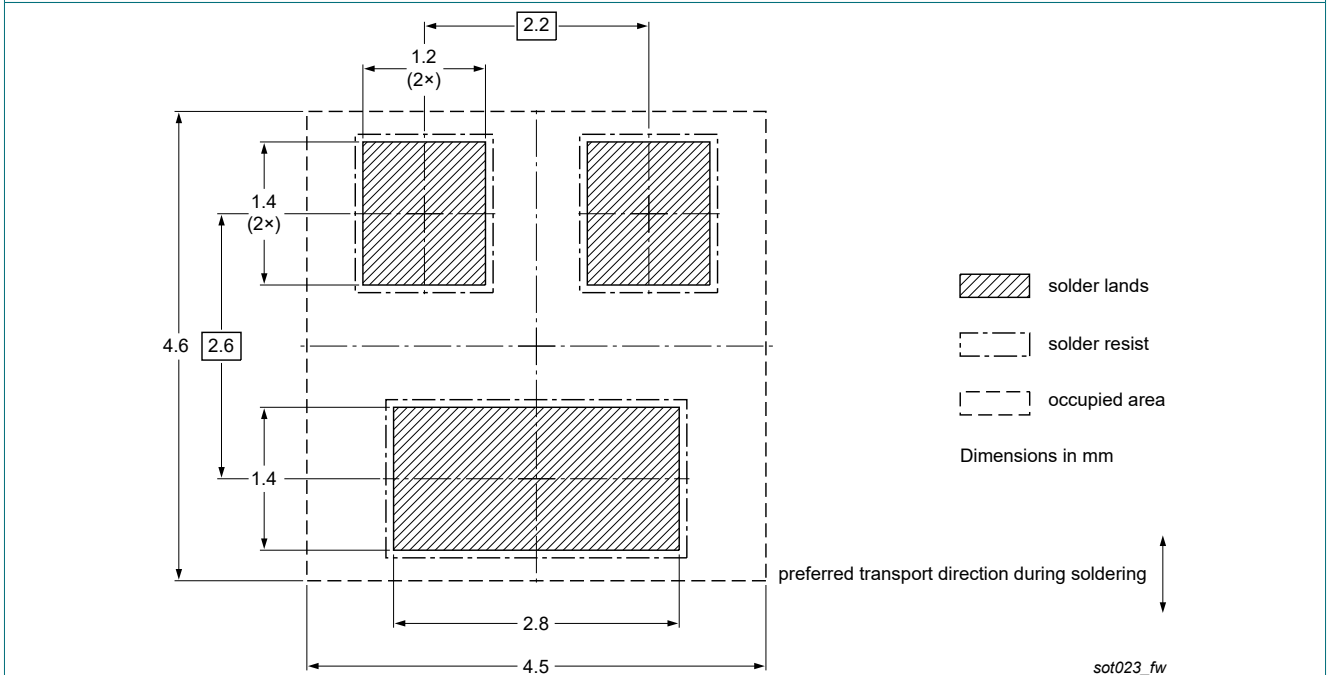


Fig. 20. Wave soldering footprint for TO-236AB (SOT23)

## 14. Revision history

Table 8. Revision history

| Data sheet ID | Release date | Data sheet status  | Change notice | Supersedes |
|---------------|--------------|--------------------|---------------|------------|
| PMV74EPE v.1  | 20190820     | Product data sheet | -             | -          |

## 15. Legal information

### Data sheet status

| Document status [1][2]         | Product status [3] | Definition  |
|--------------------------------|--------------------|---|
| Objective [short] data sheet   | Development        | This document contains data from the objective specification for product development. |
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